Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]
HP Chromebook x360 14c / Beck / 0GD

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment
1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [x] screws [] snaps [] adhesive [ ] other. Explain ______.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations. | |
Components and waste containing asbestos | |
Components, parts and materials containing refractory ceramic fibers | |
Components, parts and materials containing radioactive substances | |

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

#### Tool Description | Tool Size (if applicable)
--- | ---
screwdriver | PH00 / PH0 / PH1

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove rubber foot
2. Remove screw*6 to disassembly D cover
3. Remove battery, antenna, eDPS, fan, speaker, camera cable on chassis side
4. Remover screw *5 to disassembly battery
5. Remove screw*4 to disassembly thermal module
6. Remove screw*3 to disassembly fan
7. Remove TP, FPR, KB FFC cable on MB side
8. Remove FFC on DB side
9. Remove screw*2 to disassembly DB
10. Remove screw*3 to disassembly MB
11. Remove screw*1 to disassembly FPR module on TOP side
12. Remove TP FFC on top side
13. Remove screw*2 to disassembly speaker on TOP side
14. Remove screw*4 to disassembly hinge-up on Top-assy
15. Remove screw*7 to disassembly TP module
16. Disassembly Bezel-assay with LCD Cover-assay
17. Remove LVDS/G-sensor and TS control board on bezel-assay
18. Remove camera FFC, antenna cable on LCD cover
19. Remove screw*6 to disassembly hinge on LCD cover

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove rubber foot
   Remove screw*6 on D cover

2. Remove battery · antenna · eDPS · fan · speaker · camera cable on chassis side
   Remover screw *5 to disassembly battery

3. Remove screw*4 to disassembly thermal module
   Remove screw*3 to disassembly fan

4. Remove TP · FPR · KB FFC cable on MB side
   Remove FFC on DB side
Remove screw*2 to disassembly DB
Remove screw*3 to disassembly MB
Remove screw*1 to disassembly FPR module on TOP side
Remove TP FFC on top side

5. Remove screw*4 to disassembly hinge-up on Top-assy

6. Remove screw*7 to disassembly TP module
7. Disassembly Bezel-assy with LCD Cover-assy

8. Remove LVDS/G-sensor and TS control board on bezel-assy
9. Remove camera FFC + antenna cable on LCD cover
   Remove screw*6 to disassembly hinge on LCD cover

10. Totally disassembly parts